

11046 U.S. PRO
10/066892
03/03/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10086892	FILING DATE 03/04/2002	CLASS 438	SUBCLASS 1+	GAU 2814	EXAMINER 2813 HOGANS
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**APPLICANTS: Lee Kyo-Yeol;

**CONTINUING DATA VERIFIED: *DA*
None

** FOREIGN APPLICATIONS VERIFIED: *DA*
REPUBLIC OF KOREA 2001-11153 03/05/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials <i>DA</i>		<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 030681-366
TITLE : Method for fabricating group III-V compound semiconductor substrate U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.		Fig.s Drwg.
TERMINAL DISCLAIMER		Print Fig.		
		Application Examiner		
PREPARED FOR ISSUE				
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